



DSDT series DIP Switch

SPECIFICATION DIP SWITCH

1. Specifications

◆ Contact Rating	Switching.....	25mA, 24VDC
	Non-Switching.....	100mA, 50VDC
◆ Contact Resistance	Initial.....	50mΩ/Max
	After Reliability Test.....	100mΩ/Max.
◆ Insulation Resistance	100MΩ/Min. at 500 VDC
◆ Dielectric Strength	500VDC/ 1 mintue
◆ Operating Force	1,000g/max
◆ Travel	0.8mm
◆ Mechanical Life	3,000 cycles (Min.)
◆ Electrical Life	2,000 cycles /25mA, 24VDC
◆ Operating Temperature THT.....		-40°C ~ +85°C
◆ Storage Temperature	-40°C ~ +85°C

2. Materials:

Cover	RoHS&REACH Compliant.....	Thermoplastic UL 94V-0, Black
	Halogen Free.....	Thermoplastic UL 94-HB, Coffee
Base	RoHS&REACH Compliant.....	Thermoplastic UL 94V-0, Black
	Halogen Free.....	Thermoplastic UL 94-HB, Coffee
Actuator		Thermoplastic UL 94-HB, White
Terminal Contact		50u" +/-10u" Nickel Cover 3u" Gold-Plated
Movable Contact		50u" +/-10u" Nickel Cover 3u" Gold-Plated
Terminal		50u" +/-10u" Nickel Cover 3u" + 1u" Gold-Plated
Tape		Polyimide Fil

3. Soldering Information

◆ **Hand Soldering**

Soldering iron of 30watts or under at 350°C for 3 sec. max or at 270°C for 5 sec. Max

◆ **Reflow Soldering:**

- (1) Gold-plated types allow 2~3-time process.
- (2) Tin-plated types allow 1-time process only.
- (3) For Vapor Phase Heating (VPH) use, the switch must be tape-sealed.

◆ **Wave Soldering**

- (1) For lead free wave solder simulation of typical components, the solder bath temperature shall be maintained at 270°C max./ 5-10 seconds

◆ **Keep all actuators in "OFF" position during soldering and cleaning processes.**



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◆ Classification Reflow Profiles

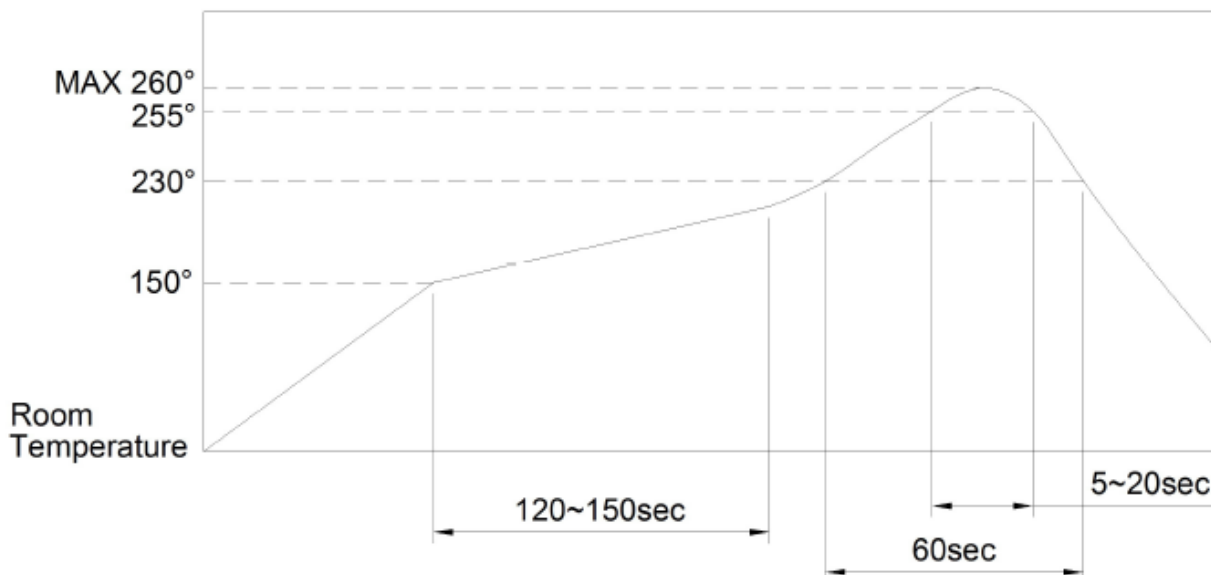
Profile Feature	Pb-Free Assembly
Preheat / Soak	
Temperature Min (T _{min})	150 °C
Temperature Max (T _{max})	200°C
Time(ts) from T _{min} to T _{max}	60 ~120 seconds
Ramp-up Rate (TL to T _p)	3°C/second max
Liquidous temperature (TL)	217°C
Time (t _L) maintained above TL	60 ~ 150 seconds
Peak package body temperature (T _p)	For users T _p must not exceed the Classification temp:260°C (Package Thickness:>2.5mm) For suppliers T _p must equal or exceed the Classification temp:260°C (Package Thickness:>2.5mm)
Time (t _p) within 5°C of specified classification Temperature (T _c)	30 seconds
Ramp-Down Rate (T _p to TL)	6°C/second max
Time 25°C to Peak Temperature	8 minutes max
# Tolerance for peak profile temperature(T _p) is defined as a supplier minimum and a user maximum	

Note 1: All temperatures refer to topside of the package, measured on the package body surface.

Note 2: Time within 5 °C of actual peak temperature (t_p) specified for the reflow profiles is a “supplier” minimum and “user” maximum.

◆ Sources: IPC/JEDEC J-STD-020D.1

Recommended Reflow Soldering Conditions



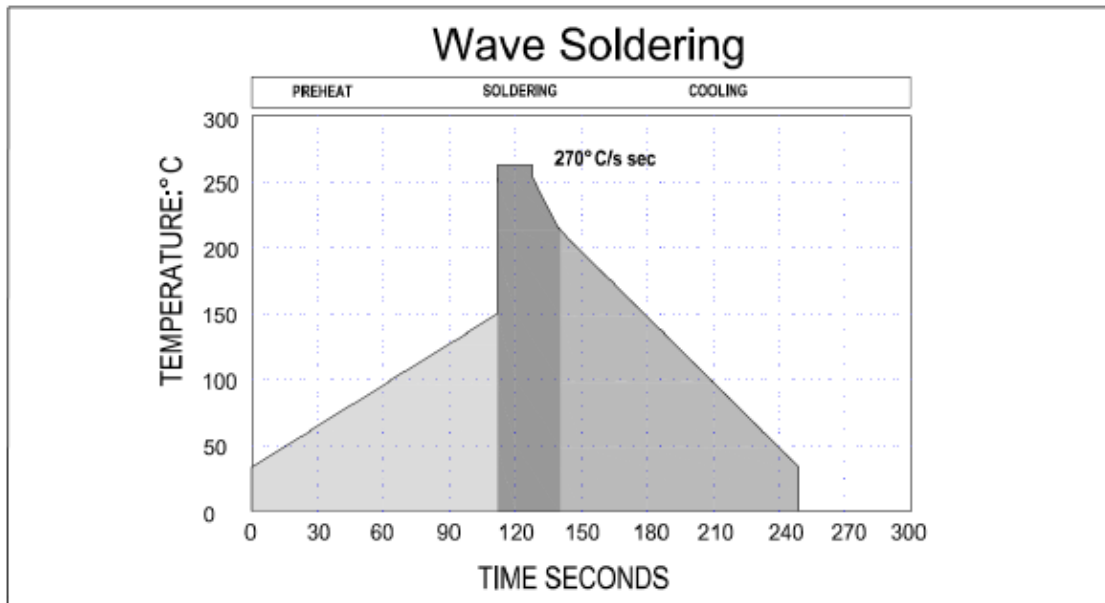


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◆ Recommended Wave Soldering Profiles



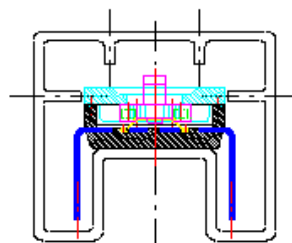
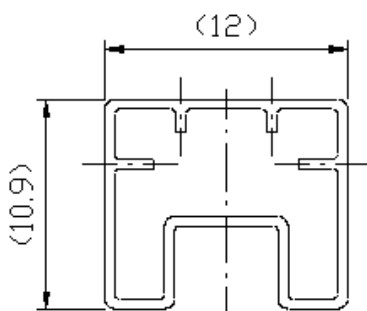
Maximum dwell time in the solder wave (270°C) shall not exceed 10 seconds.

4. Switch Operation and Taping

- (1) Use tweezers or ball-point pen for operation.
 - (2) Flux cleaning should be done without removing the Tape.
 - (3) If the tape is removed, it adheres less than before when it is placed back on possibly causing flux inflow.
 - (4) Do Not Remove Tape sealed before Reflow processing.
 - (5) Ultrasonic cleaning not recommended without Tape sealed.
- ※ All switches must set in OFF position when through Soldering process.
※ Any flux enters the switch may influence contact function.

5. Packing Specifications

DSDT Package	Pole	4	5	8	9	10
Tube	Q'ty	43	35	23	20	18



单击下面可查看定价，库存，交付和生命周期等信息

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